# Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment\*

## DIGI-KEY PART # ATS1060-ND

ATS PART # ATS-51375D-C2-R0

#### **Features & Benefits**

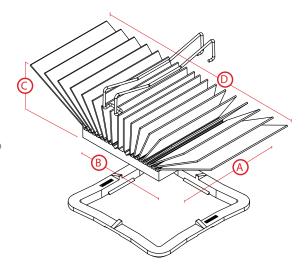
maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling

maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB

Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards

Comes preassembled with high performance, phase changing, thermal interface material

Designed for low profile components from 1.5 to 2.99mm





# **Thermal Performance Table**

AIR VELOCITY		THERMAL RESISTANCE		
FT/MIN	M/S	°C/W (UNDUCTED)	°C/W (DUCTED)	
200	1.0	4.9	3	
300	1.5	3.6		
400	2.0	3.1		
500	2.5	2.7		
600	3.0	2.5		
700	3.5	2.3		
800	4.0	2.1		

### **Product Details**†

DIMENSION A	DIMENSION B	DIMENSION C <sup>§</sup>	DIMENSION D	TIM <sup>‡</sup>	FINISH
37.5	37.5	9.5	51.36	C1100F	BLACK- ANODIZED

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or **www.qats.com** 

- \* RoHS Compliant
- ‡ TIM = Thermal Interface Material
- † Dimensions are measured in millimeters
- ◆ Dimensions A & B refer to component size
- § Dimension C = the height of the heat sink shown above and does not include the height of the attachment method



